



Scalable Flash Architectures Meet “Instant On”

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Explosion of More Intelligent and Connected Devices

2003

6.3B people



Many devices connected to the Internet

2008

6.7B people



More connected devices than people on earth

2020

7.7B people



50 – 70 billion connected devices;
~7x the number of people on earth

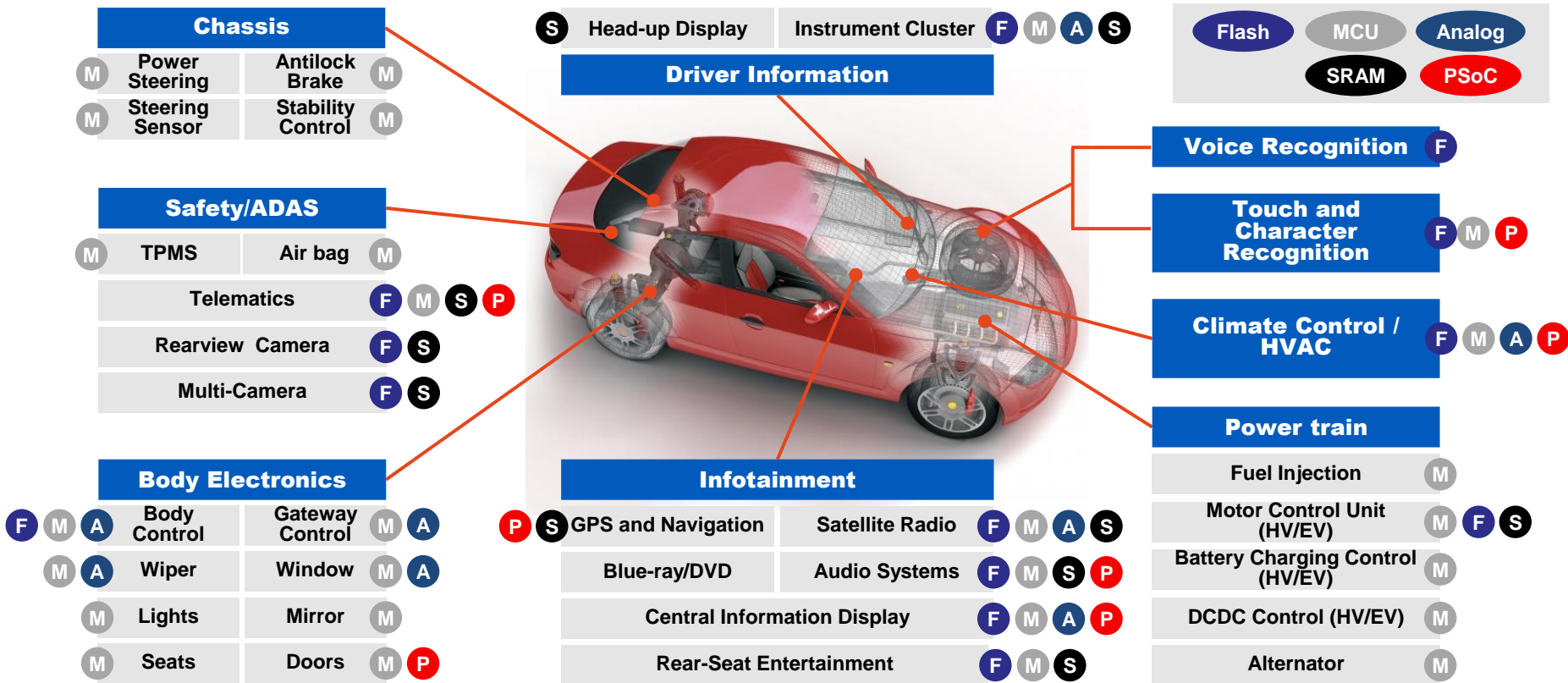
In 2013, there were 23M connected cars.

In 2015, 20% of vehicles sold will be connected.

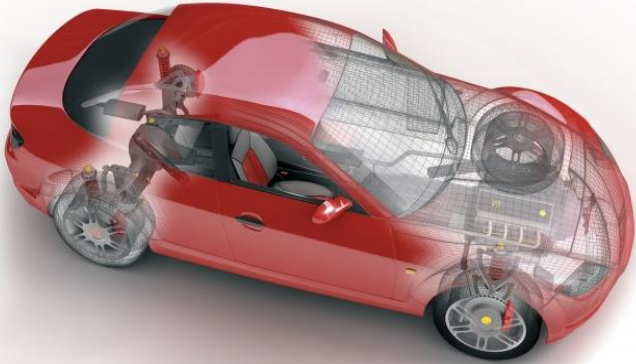
By 2020, there will be 152M connected cars sold globally. Source: IHS

Explosion of Connected Autos

Cypress + Spansion = No. 3 in Automotive Memory & MCUs



High Performance Automotive Requirements



Auto-Cluster



Infotainment

TFT replacing mechanical
Instant on

Traditional architecture insufficient
Fast boot
Graphics recall

Larger screen and higher resolution
Complex graphics
Motion graphics
More instant on functionality



**Flash NOR Flash for
Boot, Code, and Graphics**

Cypress HyperBus™: A Better Solution

HyperBus™ Interface

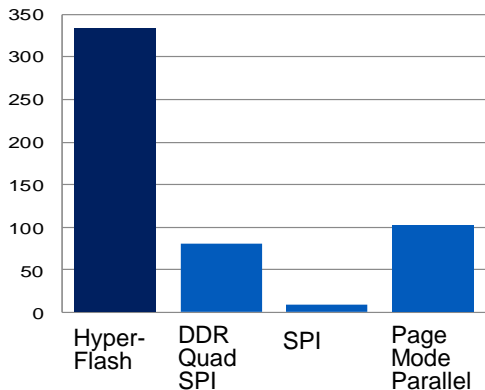
A high-bandwidth, 12-signal interface that transfers information over 8 I/O signals at double data rate (DDR), delivering up to 333 MBps

HyperFlash™ NOR Flash Memory combines the industry's **highest Read Bandwidth...**

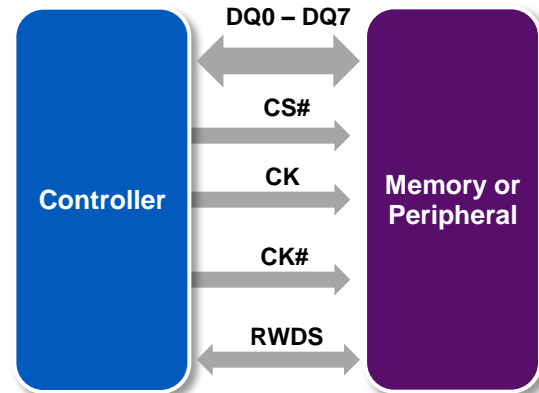
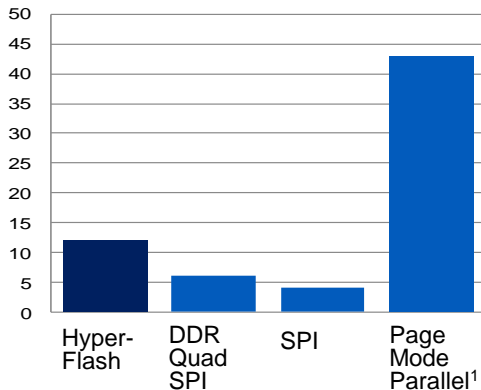
With one of the **lowest-pin-counts available...**

HyperBus™
Interface (12 pins)

Read Bandwidth (MBps)



Pins for Data Transfer (# of Pins)



HyperBus™ and HyperFlash™ Memory

Industry's fastest NOR Flash Memory for the highest-performance systems

Problems Designers Face	HyperFlash™ Solves These By:
The highest-performance systems for fast boot with graphics display	A DDR mode with up to 166-MHz with 333-MBps Read Bandwidth
Low-pin-count interfaces to reduce system cost	A standard 24-ball package sharing a common footprint with Quad SPI and Dual Quad SPI simplifies board layout
They must have high system reliability	On-chip ECC to provide a FIT rate <0.1 FIT per device
High temperature ranges	An extended operating temperature range of -40°C to +125°C

To enable demanding high-performance systems

Example:
Automotive Instrument Cluster



HyperFlash™ vs. Traditional Flash



Other

Feature	S26KS Family	2 x S25FS Family	S25FS Family	SPI
Interface	HyperBus	2 x Quad SPI	Quad SPI	Quad SPI
I/O Pin Count	8	8	4	4
Clock Rate (DDR)	166 MHz	80 MHz	80 MHz	54 -66MHz
Read DDR Bandwidth (max)	333 MBps	160 MBps	80 MBps ¹	54 - 66 MBps ¹
Program Time (512B) ²	0.475 ms	0.475 ms	0.475 ms	1.0 ms ³
Sector Erase Time (256KB) ²	930 ms	930 ms	930 ms	1400 ms ⁴
Chip Erase Time ²	110 s	120 s	120 s	240 s
Temperature Range	-40°C to +125°C	-40°C to +105°C	-40°C to +105°C	-40°C to +85°C
	Best	Better	Good	Ok

Faster Boot, Bigger Display, Higher Resolution, Fancier Graphics, Smoother Motion

¹ Calculated using DDR clock rate

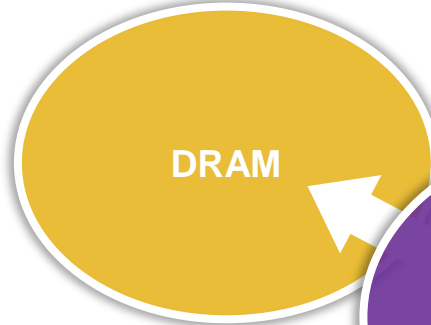
² Conditions: 25°C and V_{CC} 3.0 V, 100k minimum endurance

³ Parts do not support 512B Programming. Program time is calculated using two 256B Program operations.

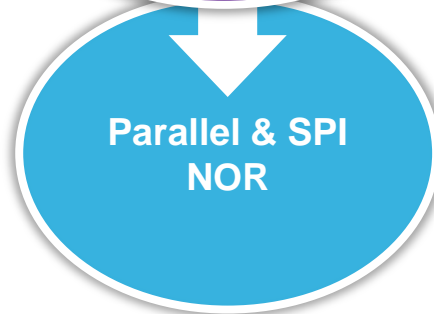
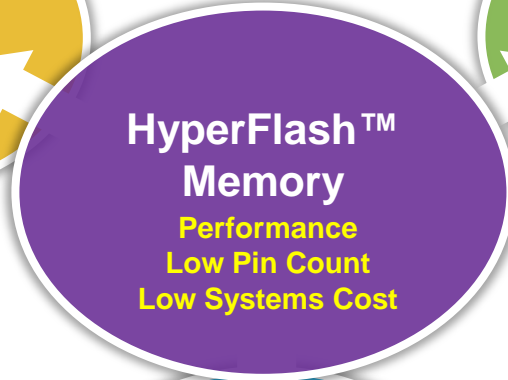
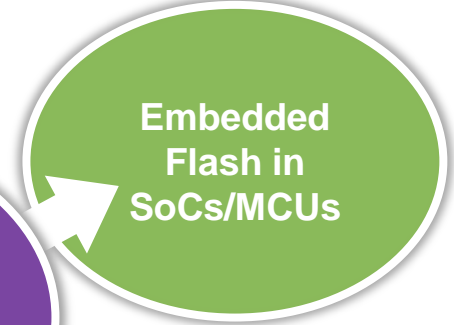
⁴ Parts do not support 256KB Sector Erase. Erase time is calculated using four 64KB Sector Erase operations.

Other Implications for High Performance Flash

Reduce or Eliminate DRAM



Flash-less SoC or Additional Flash



Alternative to Traditional NOR

- **Fast Initial Access**
- **High Sustained Read Throughput**
- **Cypress HyperRAM™ serves as a companion RAM**
 - Reduced controller pin count
 - Simplified PCB layout
 - Space-saving packaging